2SA1188, 2SA1189

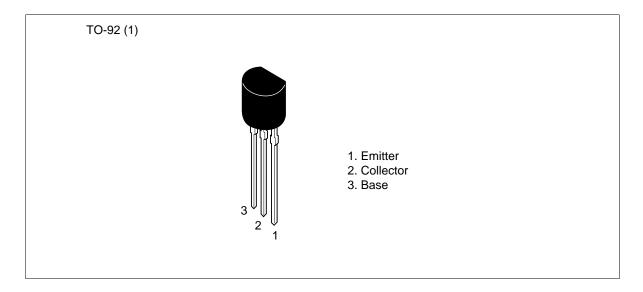
Silicon PNP Epitaxial

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Application

- Low frequency amplifier
- Complementary pair with 2SC2853 and 2SC2854

Outline





2SA1188, 2SA1189

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	2SA1188	2SA1189	Unit
Collector to base voltage	V_{CBO}	-90	-120	V
Collector to emitter voltage	V_{CEO}	-90	-120	V
Emitter to base voltage	V_{EBO}	- 5	– 5	V
Collector current	I _c	-100	-100	mA
Emitter current	I _E	100	100	mA
Collector power dissipation	P _c	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Electrical Characteristics ($Ta = 25^{\circ}C$)

		2SA1	2SA1188 2SA1189						
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-90	_	_	-120	_	_	V	$I_{c} = -10 \mu\text{A}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-90	_	_	-120	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	-5	_	_	V	$I_E = -10 \mu A, I_C = 0$
Collector cutoff current	I _{CBO}	_	_	-0.1	_	_	-0.1	μΑ	$V_{CB} = -70 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	-0.1	_	_	-0.1	μΑ	$V_{EB} = -2 \text{ V}, I_{C} = 0$
DC current trnsfer ratio	h _{FE} *1	250	_	800	250	_	800		$V_{CE} = -12 \text{ V},$ $I_{C} = -2 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	-0.05	-0.15	_	-0.05	-0.15	V	$I_{\rm C} = -10 \text{ mA},$ $I_{\rm B} = -1 \text{ mA}^{*2}$
Base to emitter saturation voltage	$V_{BE(sat)}$	_	-0.7	-1.0	_	-0.7	-1.0	V	
Gain bandwidth product	f _T	_	130	_	_	130	_	MHz	$V_{CE} = -6 \text{ V},$ $I_{C} = -10 \text{ mA}$
Collector output capacitance	Cob	_	3.2	_	_	3.2	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0,$ f = 1 MHz

Notes: 1. The 2SA1188 and 2SA1189 are grouped by $h_{\rm FE}$ as follows.

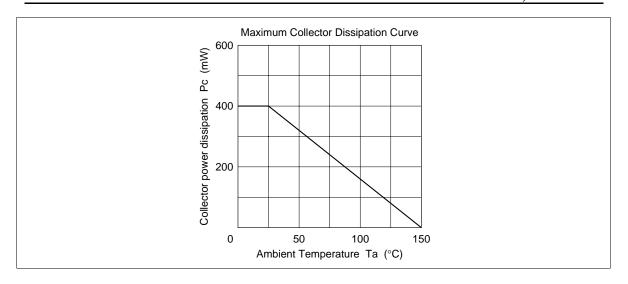
2. Pulse test

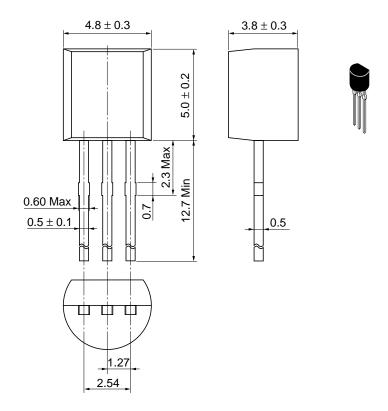
D E 250 to 500 400 to 800

See characteristic curves of 2SA1190 and 2SA1191.

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2SA1188, 2SA1189





Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

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